High Power LED Series

LH502HD Horticulture



Features & Benefits

- Operates at a maximum current of up to 1000mA
- Uniform light distribution under any beam angle
- Strengthened Anti sulfurization
- Color binning @ 85°C









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1. Characteristics

a) Absolute Maximum Rating

Item	Symbol	Rating	Unit	Condition
Operating Temperature	T_{opr}	-40 ~ +105	°C	
Storage Temperature	T_{stg}	-40 ~ +100	°C	-
LED Junction Temperature	Tj	125	°C	-
Forward Current	l _F	1000	mA	-
Peak Pulse Forward Current	l _{FP}	1250	mA	Duty cycle≤1/10, pulse width 10ms
Soldering Temperature		260 <10	°C	-
Electrostatic Discharge Withstand Voltage(HBM)	ESD(HBM)	±8 (Class 3B)	kV	-

b) Electro-optical Characteristics (I_F = 350 mA, T_j = 25 $^{\circ}\text{C}~$)

Item	Unit	Rank	Min.	Тур.	Max.
Forward Voltage (V _F)	V	YB	5.60	-	6.00
		3000K	4.75	-	5.35
PPF	umal/s	4000K	4.90	-	5.50
rer	μmol/s	5000K	5.05	-	5.65
		6500K	5.05	-	5.65
Thermal Resistance (junction to chip point)	°C/W		-	3	-
Beam Angle	0			120	

Notes:

Samsung maintains measurement tolerance of: PPF = ± 7 %, forward voltage = ± 0.1 V



2. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
c	D	ш	14/	ш	2		_	N	6	ш	0	v	D	т.	_	٨	2

Digit	PKG Information	Code			Specification				
1 2 3	Samsung Package High Power	SPH	High Power PKG						
4 5	Color	WH	White `						
6	Product Version	2	2nd Version						
7 8	Form Factor	L5	5050 size	5050 size					
9	Lens Type	N	No lens	No lens					
10	Model	6	5050 Series	5050 Series					
11	Internal Code	Н	Horticulture						
12	CRI	0							
13 14	- IV I AA	YB	Bin code	Α0	5.6 – 5.8				
15 14	Forward Voltage (V)	ΥD	Bin code	A1	5.8 – 6.0				
		٧	3000К						
15	CCT (K)	Т	4000K						
15	CCI (K)	R	5000K						
		Р	6500K						
16	MonAdom Ston	3	MacAdam 3-Ste	р					
16	MacAdam Step	5	MacAdam 5-Ste	р					
17 18	Luminous Flux (lm)	А3							

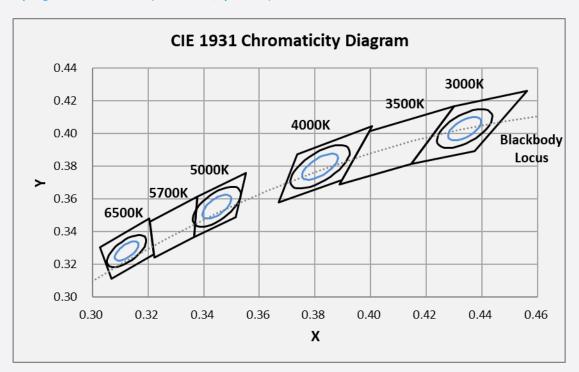
a) PPF Rank ($I_F = 350$ mA, $T_j = 25$ °C)

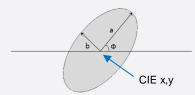
Nominal	Product Code	VF Rank	Chrom Rank	PF	PPF Range	
CCT(K)	Product Code	VF KAIIK	(Bins)	Rank	Bins	(PPF, µmol/s)
3000	SPHWH2L5N6H0YBV3A3	YB	T3, T5	A3 ·	48	4.75-5.05
	SPHWH2L5N6H0YBV5A3	10	13, 13	AS	51	5.05-5.35
4000	SPHWH2L5N6H0YBT3A3	YB	T3, T5	A3	49	4.90-5.20
4000	SPHWH2L5N6H0YBT5A3	10	13, 13	A5	52	5.20-5.50
5000	SPHWH2L5N6H0YBR3A3	YB		A3 ·	51	5.05-5.35
3000	SPHWH2L5N6H0YBR5A3	10	T3, T5	A5	54	5.35-5.65
6500	SPHWH2L5N6H0YBP3A3		T2 TE	A3 ·	51	5.05-5.35
0300	SPHWH2L5N6H0YBP5A3	YB	T3, T5	A3	54	5.35-5.65

b) Voltage Bins ($I_F = 350 \text{ mA}$, $T_j = 25^{\circ}\text{C}$)

Nominal CC (K)	T CRI (R _a) Min.	Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
			YB	Α0	5.6 – 5.8
-	-	-	16	A1	5.8 - 6.0

c) Chromaticity Region & Coordinates (I_F = 350 mA, T_j = 85°C)



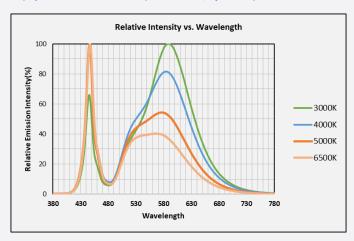


ССТ	Rank	CIE x	CIE y	Ф	А	b
3000K	V3	0.4338	0.4030	53.2	0.0083	0.0041
3000K	V5	0.4338	0.4030	55.2	0.0138	0.0068
4000K	Т3	0.3818	0.3797	53.7	0.0094	0.0040
4000K	T5		0.3797		0.0157	0.0067
5000K	R3	0.3447	0.3553	59.6	0.0082	0.0035
	R5				0.0137	0.0058
6500K	Р3	0.3123	0.3282	50.6	0.0067	0.0029
0500K	P5	0.3123	0.3262	36.0	0.0112	0.0048

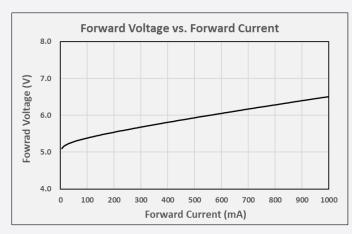
Note : Samsung maintains measurement tolerance of: Cx, $Cy = \pm 0.005$

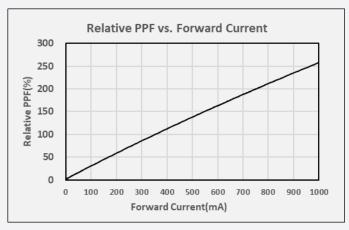
3. Typical Characteristic Graphs

a) Spectral Distribution ($I_F = 350 \text{ mA}$, $T_j = 25^{\circ}\text{C}$)

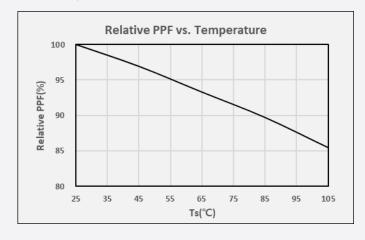


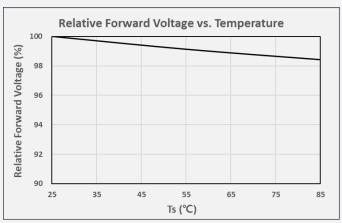
b) Forward Current Characteristics $(T_{ij} = 25^{\circ}C)$



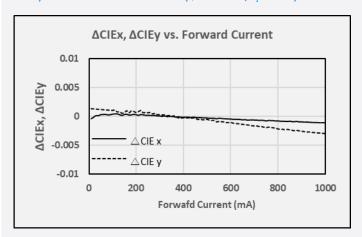


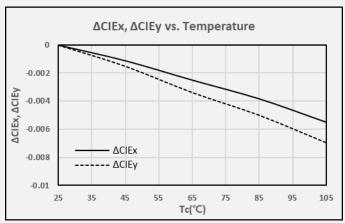
c) Temperature Characteristics (I_F = 350 mA)



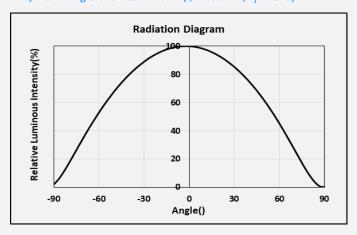


d) Color Shift Characteristics (I_F = 350 mA, T_j = 25°C)

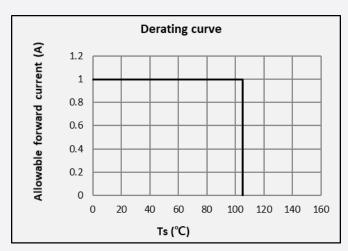




e) Beam Angle Characteristics ($I_F = 350 \text{ mA}, T_j = 25^{\circ}\text{C}$)



f) Derating Curve



g) Luminous Flux Characteristics¹⁾ (CCT = 5000K)

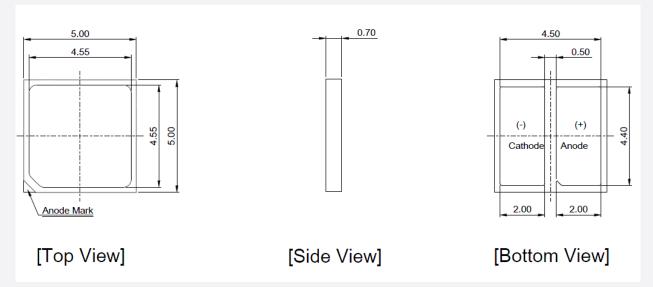
CRI (R _a)	Nominal		Typ. @ T _J = 25 °C				
Min.	ССТ (К)		V _F	PPF	PPE		
		100mA	5.37 V	1.59	2.96		
		180mA	5.51 V	3.13	2.84		
	5000K	350mA	5.70 V	5.36	2.69		
-	SUUUK	640mA	6.02 V	9.52	2.47		
		800mA	6.19 V	11.67	2.36		
		1000mA	6.40 V	14.25	2.23		

Notes:

1) Reference Only

4. Outline Drawing & Dimension

a) Mechanical Dimensions



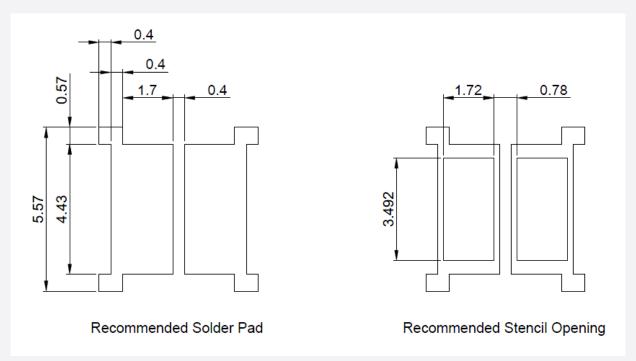
Notes:

1) Mark for the Anode

2) Unit: mm

3) Tolerance: ±0.1mm

b) Recommended Solder Pad



5. Reliability Test Items & Conditions

a) Test Items

Test Item	Test Condition	Test Hour / Cycle
High Temperature Operating Life Test	85°C, 640mA	1000 h
Wet High Temperature Operating Life Test	85℃, 85 % RH, DC 640mA	1000 h
Temperature Cycling	-45°C / 15min ~ 125°C / 15min Temperature change within 5min	500 cycles
ESD (HBM)	R1: $10 \text{ M}\Omega$ R2: $1.5 \text{ k}\Omega$ C: 100 pF V: $\pm 8 \text{ kV}$	5 times
Vibration Test	20~ 80 Hz (displacement: 0.06 inch, max. 20 g) 80 ~ 2 kHz (max. 20 g) min. frequency ↔max. frequency 4 min transfer	4 times
Mechanical Shock Test	1500g, 0.5 ms each of the 6 surfaces (3 axis x 2 sides)	5 times

b) Criteria for Judging the Damage

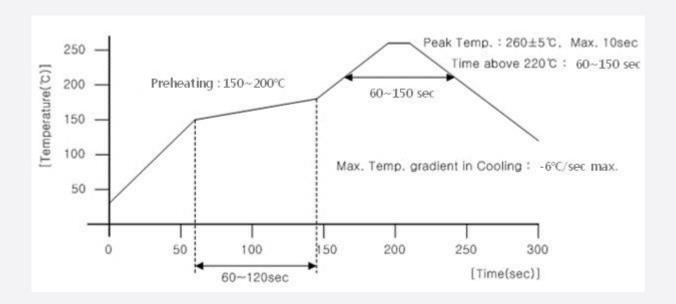
ltom	Cumbal	Test Condition	Limit			
Item	Symbol	(T _c = 25°C)	Min.	Max.		
Forward Voltage	V_{F}	I _F = Sorting Current	L.S.L. * 0.9	U.S.L. * 1.1		
PPF	μmol/s	I _F = Sorting Current	L.S.L * 0.7	U.S.L * 1.3		



6. Soldering Conditions

a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.



b) Manual Soldering Conditions

Not more than 5 seconds @ max. 300°C, under soldering iron.

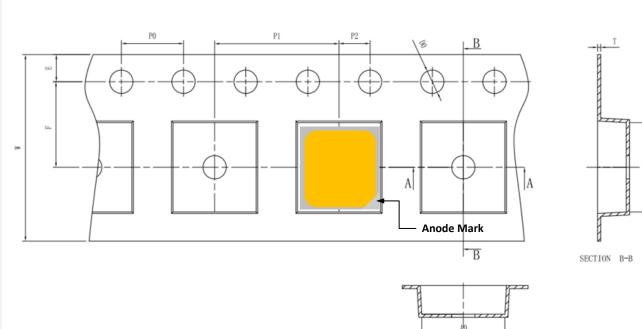
7. Tape & Reel

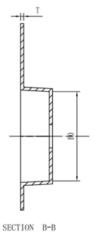
a) Taping Dimension

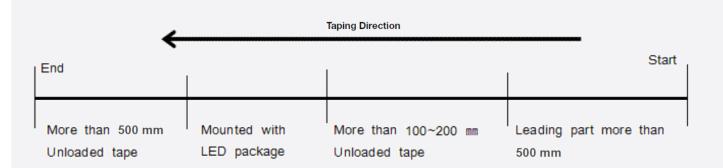
(unit: mm)

ITEM	W	A0	В0	КО	Е	F	D0	D1	P0	P1	P2	T		
DIM	12.00	5. 40	5. 20	0.95	1.75	5. 50	1.50	1.50	4.00	4.00	2.00	0.20	LENGTH	PCS/REEL
5. 35	+0. 10 -0. 10	+0. 05 -0. 05	+0. 05 -0. 05	+0. 05 -0. 05	+0. 10 -0. 10	+0. 10 -0. 10	+0. 10 -0. 00	+0. 10 -0. 00	+0. 10 0. 00	+0. 10 -0. 10	+0. 10 -0. 10	+0. 05 -0. 05	m	PCS

SECTION A-A

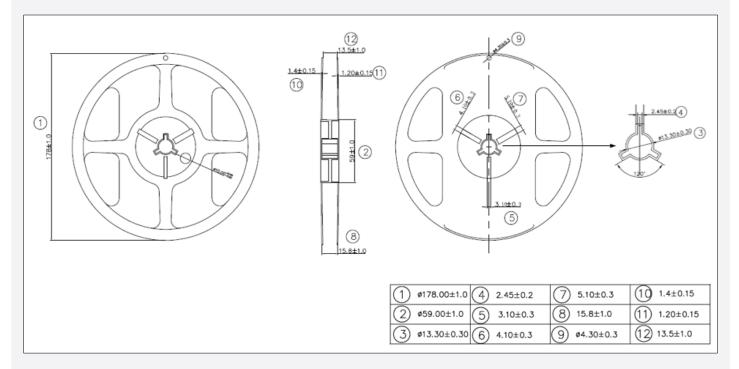






b) Reel Dimension (max 2,000 pcs)

(unit: mm)

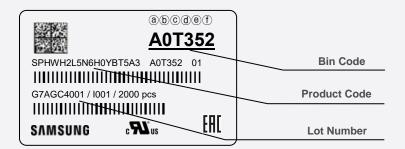


Notes:

- 1) Quantity: The quantity/reel is 2000 pcs
- 2) All dimensions are millimeters.
- 3) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag.

8. Label Structure

a) Label Structure



Note: Denoted bin code and product code above is only an example (see description on page 4)

Bin Code:

(a) (b): Forward Voltage bin (refer to page 6)(c) (d): Chromaticity bin (refer to page 7)(e) (f): PPF bin (refer to page 5)

b) Lot Number

The lot number is composed of the following characters:



123456789/Iabc / xxxx pcs

(1)(2) : Production site (G7 : Guangzhou ,China)

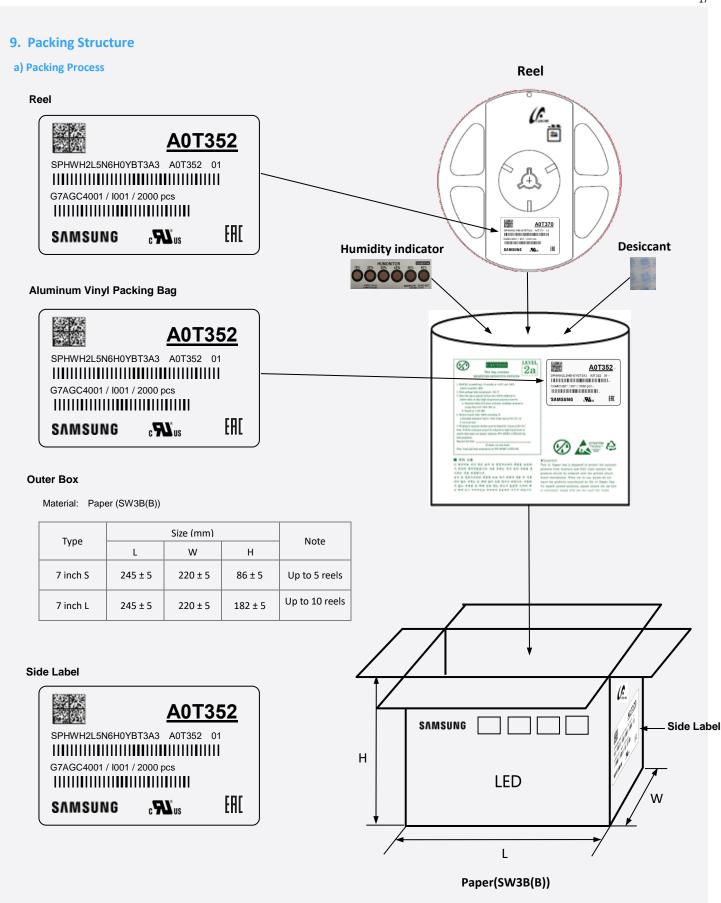
(3) : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)

(4) : Year (G:2022, H:2023 ...)

(5) : Month (1-9, A, B, C)(6) : Day (1-9, A, B-V)

(7) (8) 9 : Samsung Electronics Product serial number (001 - 999)

(a) (b) (c) : Reel number (001 - 999)



b) Aluminum Vinyl Packing Bag



CAUTION



This bag contains MOISTURE SENSITIVE DEVICES

- Shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
- 2. Peak package body temperature: 240 °C
- After this bag is opened, devices that will be subjected to reflow solder or other high temperature processes must be:
 - a. Mounted within 672 hours at factory conditions of equal to or less than 30°C /60% RH, or
 - b. Stored at < 10% RH
- 4. Devices require bake, before mounting, if:
 - a.Humidity Indicator Card is > 60% when read at 23±5°C, or b. 2a is not met.
- 5. If baking is required, devices must be baked for 10~24 hours at 60±5°C Note: if device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure,

Bag seal due date:

(I blank, see code label)

Note: Level and body temperature by IPC/JEDEC J-STD-020



A0T352

SPHWH2L5N6H0YBT3A3 A0T352 01

G7AGC4001 / I001 / 2000 pcs

SAMSUNG

c**W**us

FAI









■ 주의 사항

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■ Important

This Al Zipper bag is designed to protect the enclosed products from moisture and ESD. Once opened, the products should be soldered onto the printed circuit board immediately. When not in use, please do not leave the products unprotected by the Al Zipper Bag. To repack unused products., please ensure the zip-lock is completely sealed with the dry pack left inside.

c) Silica Gel & Humidity Indicator Card inside Aluminum Vinyl Bag

(This image is for reference only. Silicagel and humidity indicator shapes may be different.)





10. Precautions in Handling & Use

- 1) For over-current protection, users are recommended to apply resistors connected in series with the LEDs to mitigate sudden change of the forward current caused by shift of forward voltage.
- 2) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.
- 3) When the device is in operation, the forward current should be carefully determined considering the maximum ambient temperature and corresponding junction temperature.
- 4) LEDs must be stored in a clean environment. Shelf life of sealed bags is 12 months at temperature 0~40℃, 0~90 % RH.
- 5) After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
 - a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30° C / 60° M RH, or
 - b. Stored at <10 % RH
- 6) Repack unused devices with anti-moisture packing, fold to close any opening and then store in a dry place.
- 7) Devices require baking before mounting, if humidity card reading is >60 % at 23 \pm 5°C
- 8) Devices must be baked for 1 hour at $60 \pm 5^{\circ}$ C, if baking is required.
- 9) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- 10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.
- 11) Risk of sulfurization (or tarnishing)
 - The LED from Samsung Electronics Co., Ltd. uses a silver-plated lead frame and its surface color may change to black (or dark colored) when it is exposed to sulfur (S), chlorine (Cl) or other halogen compound. Sulfurization of lead frame may cause intensity degradation, change of chromaticity coordinates and, in extreme cases, open circuit. It requires caution. Due to possible sulfurization of lead frame, LED should not be used and stored together with oxidizing substances made of materials such as: rubber, plain paper, lead solder cream, etc.



Legal and additional information.

About Samsung Electronics Co., Ltd.

transformative ideas and technologies, redefining the worlds of TVs, smartphones, wearable devices, tablets, cameras, digital appliances, printers, medical equipment, network systems and semiconductors.

We are also leading in the Internet of Things space through, among others, our Digital Health and Smart Home initiatives. We employ 307,000 people across 84 countries. To discover more, please visit our official website at www.samsung.com and our official blog at global.samsungtomorrow.com.

"Samsung provides limited warranty for its LED products, the full text of which is available at https://www.samsung.com/led/lighting/warranty."

Samsung Electronics Co., Ltd. inspires the world and shapes the future with

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